

# **TAKPOXY-219**

## **EPOXY NOVOLAC RESIN**

### **1. Product description**

This is a two-component, high-temperature thermosetting epoxy system. Component A is based on a DGEBA epoxy resin blended with 20% novolac epoxy resin. The resin blend is specified at an **epoxy equivalent weight (EEW) of 210 g/eq**. Component B is a **modified aromatic polyamine** curing agent. The cured network is intended for structural bonding, encapsulation, tooling, electrical insulation, and protective coating applications where elevated-temperature performance is required.

The stated service capability is **up to 195 °C**, subject to validated continuous/intermittent exposure limits, thermal cycling, applied stress, chemical environment, film or bond-line thickness, and the actual post-cure. The 195 °C statement should not be interpreted as an unconditional continuous-use rating until supported by long-term aging and property-retention testing.

### **2. Formulation and mix-ratio basis**

| <b>Item</b>                     | <b>Component A: resin blend</b> | <b>Component B: hardener</b>                                 |
|---------------------------------|---------------------------------|--------------------------------------------------------------|
| Chemistry                       | DGEBA + 20% novolac epoxy resin | Modified aromatic polyamine                                  |
| Designation                     | Epoxy resin blend               | Amine curing agent                                           |
| Equivalent-weight input         | EEW = 210 g/eq                  | AHEW = 90 g/eq*                                              |
| Recommended mix ratio by weight | 100                             | 42.9*                                                        |
| Stoichiometric basis            | 100 parts                       | 42.9 parts by weight;<br>calculated as $100 \times 90 / 210$ |
| Mix-ratio tolerance             | Target $\pm 2\%$ by weight      | Target $\pm 2\%$ by weight                                   |

\*Using the specified EEW and AHEW, the nominal stoichiometric ratio is **100 parts by weight of Component A to 42.9 parts by weight of Component B**, or **2.33:1 by weight**. This is calculated as  $100 \times 90 / 210 = 42.86$ . The final formulation may require an intentional stoichiometric offset for toughness, cure speed, chemical resistance, or high-temperature retention; any such offset must be documented by the formulator. The stated EEW and AHEW should be confirmed by the latest certificates of analysis before production release.

### 3. Recommended processing and cure

| Parameter                                | Recommended starting point                          | Verification requirement                              |
|------------------------------------------|-----------------------------------------------------|-------------------------------------------------------|
| Conditioning before mixing               | 23 ± 2 °C                                           | Record component temperatures                         |
| Mixing                                   | 3–5 min, low-shear; scrape vessel walls             | Avoid entrained air and localized exotherm            |
| Degassing                                | 5–15 min under vacuum, if compatible                | Confirm no foaming or volatile loss                   |
| Working temperature                      | 20–30 °C                                            | Higher temperatures reduce viscosity and pot life     |
| Initial cure                             | 2–4 h at 80 °C                                      | Establish by DSC/DMA and gel-time testing             |
| Post-cure                                | 2 h at 120 °C + 2 h at 160 °C, with controlled ramp | Optimize for Tg and thermal aging                     |
| Suggested final post-cure for 200 °C use | 2 h at 180 °C after the above schedule              | Do not exceed substrate or assembly limits            |
| Maximum mixed-mass batch                 | Establish by adiabatic/exotherm testing             | Depends strongly on batch size and container geometry |

These are starting conditions only. A qualified process engineer should establish the actual cure window using differential scanning calorimetry, gel time, DMA, hardness development, and property-retention testing.

### Thermal Properties

| Property                                            | Test Method        | Typical Value    |
|-----------------------------------------------------|--------------------|------------------|
| Glass Transition Temperature (Tg), DMA tan $\delta$ | ASTM D7028 / D4065 | 170 – 195 °C     |
| Glass Transition Temperature (Tg), DSC              | ASTM E1356         | 160 – 185 °C     |
| Heat Deflection Temperature (HDT)                   | ASTM D648          | 150 – 180 °C     |
| Coefficient of Thermal Expansion, below Tg          | ASTM E831          | 55 – 65 ppm/°C   |
| Coefficient of Thermal Expansion, above Tg          | ASTM E831          | 150 – 200 ppm/°C |
| Decomposition Onset (5% weight loss, TGA)           | ASTM E1131         | 350 – 380 °C     |
| Thermal Conductivity                                | ASTM E1461         | ~0.20 W/m·K      |

### Mechanical Properties (Room Temperature, Unfilled)

| Property                       | Test Method | Typical Value                  |
|--------------------------------|-------------|--------------------------------|
| Tensile Strength               | ASTM D638   | 70 – 90 MPa                    |
| Tensile Modulus                | ASTM D638   | 3.0 – 3.5 GPa                  |
| Elongation at Break            | ASTM D638   | 2 – 5 %                        |
| Flexural Strength              | ASTM D790   | 110 – 140 MPa                  |
| Flexural Modulus               | ASTM D790   | 3.2 – 3.8 GPa                  |
| Compressive Strength           | ASTM D695   | 110 – 140 MPa                  |
| Izod Impact Strength (Notched) | ASTM D256   | 15 – 25 J/m                    |
| Fracture Toughness (K1c)       | ASTM D5045  | 0.6 – 0.9 MPa·m <sup>0.5</sup> |
| Hardness (Shore D)             | ASTM D2240  | 85 – 90                        |

## Physical Properties

| Property                       | Test Method | Typical Value                 |
|--------------------------------|-------------|-------------------------------|
| Cured Density                  | ASTM D792   | 1.20 – 1.25 g/cm <sup>3</sup> |
| Water Absorption (24 h, 23 °C) | ASTM D570   | 0.1 – 0.3 %                   |
| Cure Shrinkage (Volumetric)    | —           | 1 – 3 %                       |

## Electrical Properties

| Property                    | Test Method | Typical Value                            |
|-----------------------------|-------------|------------------------------------------|
| Dielectric Strength         | ASTM D149   | 16 – 20 kV/mm                            |
| Volume Resistivity          | ASTM D257   | 10 <sup>15</sup> – 10 <sup>16</sup> Ω·cm |
| Dielectric Constant @ 1 MHz | ASTM D150   | 3.8 – 4.5                                |
| Dissipation Factor @ 1 MHz  | ASTM D150   | 0.01 – 0.03                              |

## Formulation Notes

- The epoxy novolac fraction is the primary driver of Tg/HDT and chemical resistance above what an unmodified DGEBA/amine system would provide (~120–140 °C HDT); the higher-functionality network requires the full 180–200 °C post-cure to develop.
- Under-curing or omitting the post-cure step will leave Tg and mechanical properties well below the values listed above.
- The exotherm from a stoichiometric aromatic-amine cure can be significant in thick sections; void content and cure uniformity in mass castings will affect real-world mechanical performance more than small formulation adjustments.
- Values assume a void-free, fully cured, unfilled casting. Fillers, reinforcement, or process defects (voids, incomplete wet-out) will shift these numbers.

## **6. Chemical and environmental resistance — expected performance**

The cured system is expected to show good resistance to water, dilute acids, dilute alkalis, salts, oils, and many hydrocarbons. Performance is formulation- and exposure-dependent. Strong oxidizing acids, concentrated acids or alkalis, selected ketones, chlorinated solvents, polar aprotic solvents, and prolonged hot-water exposure may cause swelling, plasticization, loss of adhesion, or degradation. Test representative coupons at the intended temperature and concentration before approving service.

## **7. Application guidance**

Surfaces should be clean, dry, and free of oil, release agent, dust, and weak oxide. Metals should normally be abraded or grit-blasted and solvent-wiped with a compatible solvent. Do not apply to a wet or actively outgassing substrate. Use accurate weighing, thorough low-shear mixing, and controlled cure. Avoid thick masses unless the exotherm has been characterized, because epoxy/amine reactions are exothermic and can produce excessive heat.

## **8. Packaging, storage, and handling**

Store Components A and B separately in tightly closed, original containers at 5–25 °C, protected from moisture, direct sunlight, ignition sources, and contamination. Allow cold material to reach processing temperature before opening where condensation could occur. Do not return mixed material to the original containers. Follow the accompanying SDS, use suitable chemical-resistant gloves and eye protection, and provide local exhaust ventilation where vapors, aerosols, or heated material may be generated.

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